

Process/SIP Application Form(Check List)

Before mailing the application documents, it is recommended that you verify that all documents have been secured according to the following “Check List.”

1. “Process Information Usage Application Form” (The applied processes do not need to submit this document repeatedly.)
 - ☐ The professor signs and fills out the identification number.
 - ☐ Affix the department seal.
 - ☐ Foreign professors are required to provide an effective copy of their employment certificate and a copy of their Alien Resident Certificate.
2. [List of Users]
 - ☐ Fill out the process code of the application submission.
 - ☐ Fill out information pertaining to the authorized user (student or researcher).
 - ☐ Attach a copy of the front and back of the student ID, **along with the registration seal or proof of enrollment for the current semester**, and **bind the document at the back**.
 - ☐ Researchers are required to provide the following documents: ①copy of the valid appointment letter from the university. ② Valid supporting documents of employment relationship between the researcher and the applicant (professor).
 - ☐ A copy of the valid **Alien Resident Certificate (ARC)** should be attached if the authorized user is a foreigner.
 - ☐ The professor should affix his or her signature below the [List of Users].
3. Download and Input the List of Users (Excel File): (To prevent the system program from becoming unable to read, refrain from modifying the file content column and setting.)
 - ☐ Email to tsri-process@nlar.org.tw.
4. TSMC NDA (Applicable for EDA Cloud processes.)
 - ☐ After entering the information in the NDA attachment, **two copies** should be signed by the authorized users.
5. Others (Please submit other documents according to the application requirements of the EDA Cloud/General/ TSMC FinFET Program processes):
 - ☐ Semiconductor Intellectual Property Usage Application Form (applicable for the IPs of partial processes): Request the signature of the professor, fill out the professor’s identification number, and affix the department seal.
 - ☐ TSMC FinFET Program NDA Attachment(Exhibit C- Acknowledgement Form & Exhibit E;Applicants for ADFP process are not required to submit)

(Mail/Deliver the above documents to No.26, Prosperity Road I, Hsinchu Science Park, Hsinchu 300091, Taiwan, R.O.C., Taiwan Semiconductor Research Institute (TSRI) Process/SIP Application)